

# **Product/process change notification**

PCN N° 2021-178-A

Dear customer,

Please find attached our Infineon Technologies AG PCN:

#### Introduction of alternate lead frame base material affecting TSNP products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2021-12-22
- Infineon aligns with the widely recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress. We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance. For further details, please visit our website: https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/

Infineon Technologies AG

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# **Product/process change notification**

### PCN N° 2021-178-A

- ► **Products affected** Please refer to attached affected product list 1\_cip21178\_A
- Detailed change information

Subject	Introducing new lead frame base material C7025 at JCET, which is already a qualified material for Infineon product, to assure supply continuity.		
Reason	JCET Group's lead frame supplier, HAESUNG DS CO., LTD. (HDS), has announced discontinuation of supplying lead frame with EFTEC as base material.		
Description	<u>Old</u>	New	
	<ul> <li>LF base material =</li> </ul>	<ul> <li>LF base material =</li> </ul>	
	EFTEC64T	EFTEC64T or C7025	
<ul> <li>Product identification</li> </ul>	Internal traceability ensured via lot number & date code. No change in SP ordering number.		
<ul> <li>Impact of change</li> </ul>	<b>No</b> change on package outline dimensions <b>No</b> impact on solderability, thermal and electrical parameters <b>No</b> impact on quality, function and reliability as proven in process qualification		
<ul> <li>Attachments</li> </ul>	1_cip21178_Aaffected product list3_cip21178_Aadditional information		
► Time schedule			
<ul> <li>Final qualification report</li> </ul>	2022-01-31 Refer to 3_cip21178_A		
<ul> <li>First samples available</li> </ul>			

Intended start of delivery 2022-02-15

If you have any questions, please do not hesitate to contact your local sales office.



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Sales name	SP number	OPN	Package
BGA 5H1BN6 E6327	SP001777994	BGA5H1BN6E6327XTSA1	TSNP-6-10
BGA 824N6 E6329	SP002478900	BGA824N6E6329XTSA1	TSNP-6-10
BGA 855N6 E6327	SP002337750	BGA855N6E6327XTSA1	TSNP-6-10
BGS 12WN6 E6327	SP002203570	BGS12WN6E6327XTSA1	TSNP-6-10
BGA 9C1MN9 E6327	SP002367712	BGA9C1MN9E6327XTSA1	PG-TSNP-9-6
BGA 9V1MN9 E6327	SP002367704	BGA9V1MN9E6327XTSA1	PG-TSNP-9-6